



**Surface Mount Glass Passivated
Bridge Rectifiers
贴片式玻璃钝化整流桥**

**Reverse Voltage - 50 to 1000 Volts
反向电压 50-1000V
Forward Current - 3.0 Amperes
正向电流 3.0A**

Features 特征

- Compact, Thin Profile Package Design 紧凑，薄的封装外形设计
- Ideal for SMT manufacturing 适用于制造业
- Reliable robust construction 可靠的结构

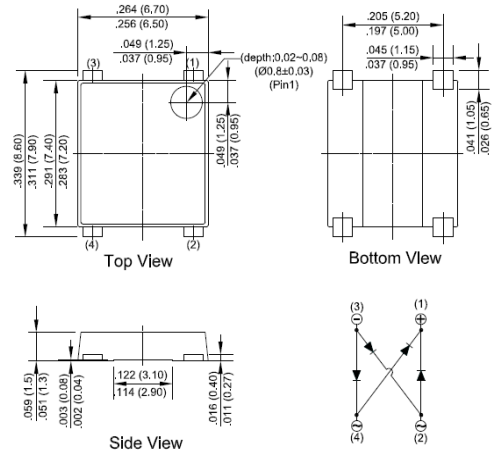
Mechanical Data 外观信息

- Polarity: Symbol marked on body 极性：标志在产品的本体上
- Mounting position: Any 安装位置：任何位置

Applications 应用

- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.
一般应用于交流/直流桥式全波整流，如：开关电源，照明镇流器、适配器等。

MSBL



Package Outline Dimensions in Inches (Millimeters)

封装外观尺寸单位英寸（毫米）

Maximum Ratings and Electrical Characteristics 最大额定值及电气特性

Rating at 25°C ambient temperature unless otherwise specified. 环境温度25°C，除非特别说明。

Single phase, half wave, 60Hz, resistive or inductive load. 单相半波，60Hz，阻性或感性负载。

For capacitive load, derate current by 20%. 对于电容性负载，降低20%的额定电流。

Characteristics 特性	Symbol 符号	MSB 30A	MSB 30B	MSB 30D	MSB 30G	MSB 30J	MSB 30K	MSB 30M	Unit 单位
Maximum Repetitive Peak Reverse Voltage 最大重复峰值反向电压	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage 最大有效反向电压	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage 最大直流阻断电压	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @Tc=120 ℃ (Note1) 最大正向平均整流电流	I(AV)	3.0							A
Peak Forward Surge Current @ 8.3ms Single Half Sine-Wave @ 1.0ms 单一正弦半波叠加在额定负载上的浪涌能力（JEDEC方法）	IFSM	100 200							A
I²t Rating for Fusing (1ms < t < 8.3ms) 熔断额定值 (1ms < t < 8.3ms)	I²t	41.5							A²s
Peak Forward Voltage Per Diode at 1.5A DC 单个二极管在1. 5A电流下的正向峰值电压	VF	1.02							V
Peak Forward Voltage Per Diode at 3.0A DC 单个二极管在3. 0A电流下的正向峰值电压	VF	1.1							V
Maximum DC Reverse Current at Rated @Tj=25℃ DC Blocking Voltage per Diode @Tj=125℃ 单个二极管在额定直流电压下的最大反向直流电流	Ir	5 500							μA
Typical Junction Capacitance per Diode (Note1) 典型结电容（备注2）	CJ	35							pF
Typical Thermal Resistance to Ambient (Note2) 结到环境的典型热阻值（备注2）	RθJA	25							℃/W
Typical Thermal Resistance to case (Note2) 结到壳的典型热阻值（备注2）	RθJC	8							
Typical Thermal Resistance to lead (Note2) 结到引线的典型热阻值（备注2）	RθJL	15							
Operating Junction Temperature Range 结温工作范围	TJ	-55 to +150							℃
Storage Temperature Range 储存温度范围	TSTG	-55 to +150							℃

Notes 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC. 在 1.0MHz 下和反向电压为 4.0V DC 下测试。

2. Thermal Resistance test performed in accordance with JESD-51. Unit mounted on glass-epoxy substrate with 1oz/ft² 20x20 mm copper pad per pin.

3. The typical data above is for reference only(典型值仅供参考).

Fig. 1 - Forward Current Derating Curve

图1 正向电流降额曲线

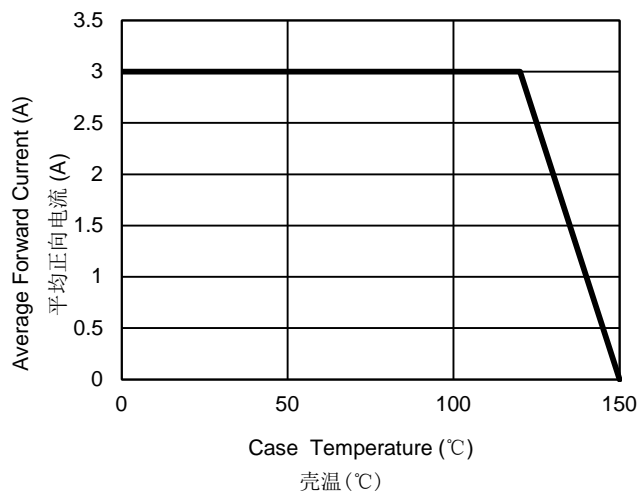


Fig. 2 - Maximum Non-Repetitive Surge Current

图2 最大不重复正向浪涌曲线

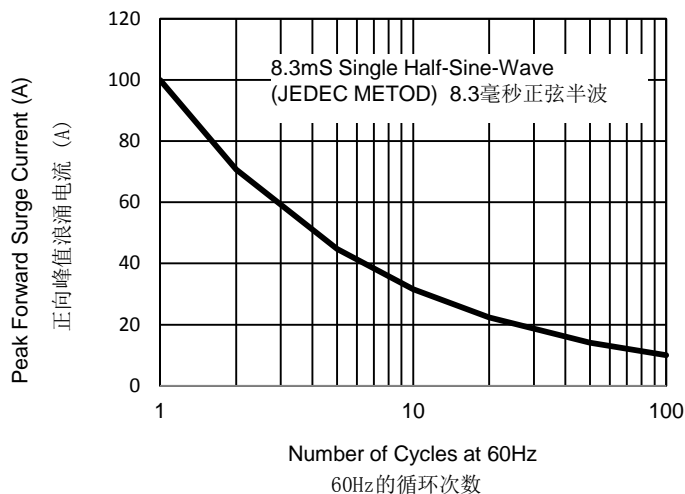


Fig. 3 - Typical Reverse Characteristics

图3 典型的反向特性

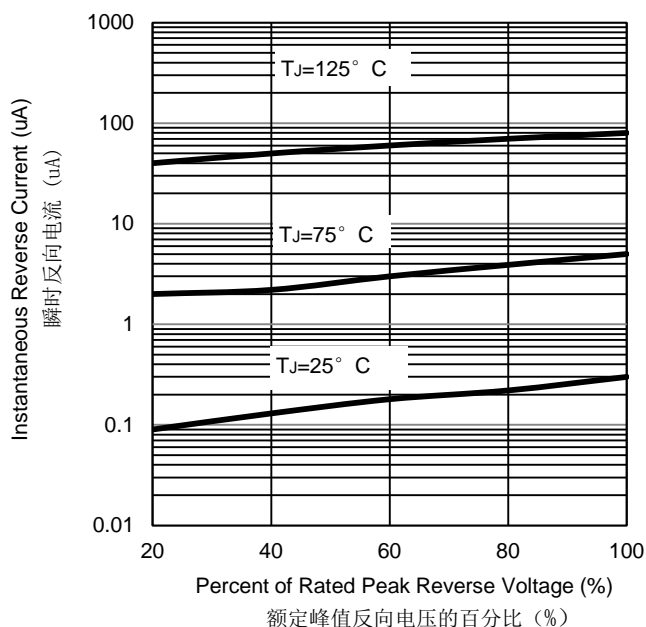


Fig. 4 - Typical Forward Characteristics

图4 典型的正向特性

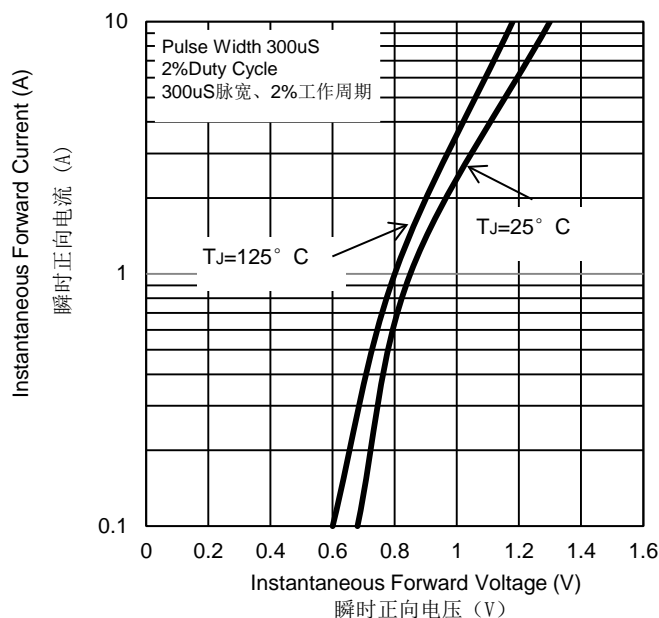
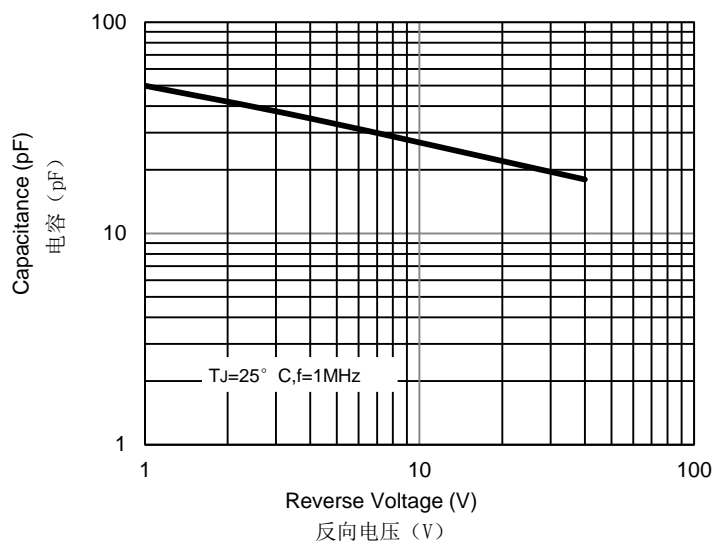


Fig. 5 - Typical Junction Capacitance

图5 典型的结电容





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